MTM86124

Silicon P-channel MOS FET

For DC-DC converter circuits For switching circuits

Overview

MTM86124 is the P-channel MOS FET that is highly suitable for DC-DC converter and other switching circuits.

Features

- Low ON resistance: $R_{on} = 100 \text{ m}\Omega (V_{GS} = 4.0 \text{ V})$
- Low short-circuit input capacitance (common source): $C_{iss} = 400 \text{ pF}$
- Small package: WSSMini6-F1 (1.6 mm × 1.6 mm × 0.5 mm)
- Low drive voltage: 2.5 V drive

Absolute Maximum Ratings $T_a = 25^{\circ}C$

| Parameter | Symbol | Rating | Unit |
|--------------------------------|------------------|-------------|------|
| Drain-source surrender voltage | V _{DSS} | -20 | V |
| Gate-source surrender voltage | V _{GSS} | ±10 | V |
| Drain current | ID | -2.0 | А |
| Peak drain current *1 | I _{DP} | -8 | А |
| Power dissipation *2 | P _D | 540 | mW |
| Channel temperature | T _{ch} | 150 | °C |
| Storage temperature | T _{stg} | -55 to +150 | °C |



Code

| WSSMini6-F1 |
|-------------|
|-------------|

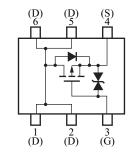
| • | Pin | Name | |
|---|-----|------|--|
| | | | |

| 1: Drain | 4: Source |
|----------|-----------|
| 2: Drain | 5: Drain |
| 3: Gate | 6: Drain |

6: Drain

Marking Symbo: DM

Internal Connection



Note) *1:Pulse width $\leq 10 \ \mu$ s, Duty cycle $\leq 1\%$

*2:Measuring on ceramic substrate at 40 mm \times 38 mm \times 0.2 mm

 $P_{\rm D}$ absolute maximum rating without a heat shink: 150 mW

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|--|-----------------------|---|-------|--------|------|------|
| Drain-source surrender voltage | V _{DSS} | $I_{\rm D} = -1 {\rm mA, V_{\rm GS}} = 0$ | -20 | | | V |
| Drain-source cutoff current | I _{DSS} | $V_{DS} = -20 \text{ V}, V_{GS} = 0$ | | | -1.0 | μΑ |
| Gate-source cutoff current | I _{GSS} | $V_{GS} = \pm 8 \text{ V}, V_{DS} = 0$ | | | ±10 | μΑ |
| Gate threshold voltage | V _{TH} | $I_{\rm D} = -1.0 \text{ mA}, V_{\rm DS} = -10 \text{ V}$ | - 0.4 | - 0.85 | -1.3 | V |
| Drain-source ON resistance 1 ^{*1} | R _{DS(on)} 1 | $I_{\rm D} = -1$ A, $V_{\rm GS} = -4.0$ V | | 100 | 130 | mΩ |
| Drain-source ON resistance 2 ^{*1} | R _{DS(on)} 2 | $I_{\rm D} = -0.6$ A, $V_{\rm GS} = -2.5$ V | | 130 | 200 | mΩ |
| Forward transfer admittance ^{*1} | Y _{fs} | $I_D = -1.0 \text{ A}, V_{DS} = -10 \text{ V}, f = 1 \text{ kHz}$ | 3.0 | | | S |
| Short-circuit input capacitance (Common source) | C _{iss} | | | 400 | | pF |
| Short-circuit output capacitance (Common source) | C _{oss} | $V_{DS} = -10 V, V_{GS} = 0, f = 1 MHz$ | | 40 | | pF |
| Reverse transfer capacitance (Common source) | C _{rss} | | | 35 | | pF |
| Turn-on time *2 | t _{on} | $V_{DD} = -10 \text{ V}, V_{GS} = 0 \text{ V to } -4 \text{ V}, I_D = -1 \text{ A}$ | | 15 | | ns |
| Turn-off time *2 | t _{off} | $V_{DD} = -10 \text{ V}, V_{GS} = -4 \text{ V to } 0 \text{ V}, I_D = -1 \text{ A}$ | | 100 | | ns |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

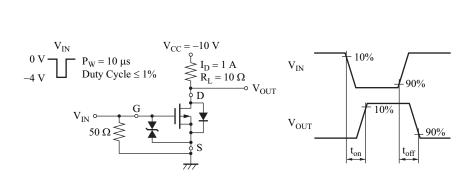
2. *1: Pulse measurement

*2: Test circuit

MTM86124

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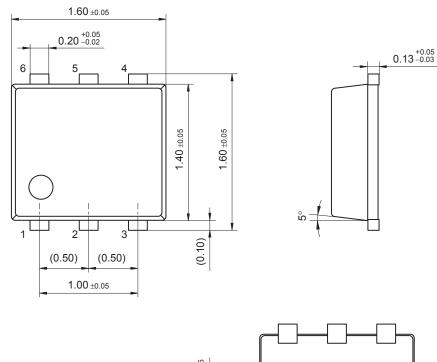
Test circuit

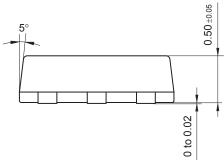


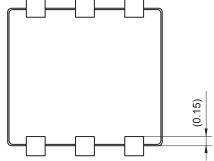
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WSSMini6-F1

Unit: mm







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